

L Number	Hits	Search Text	DB	Time stamp
1	1016389	copper or Cu	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2003/10/31 18:59
2	423795	adhesion	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2003/10/31 18:59
3	178820	seed	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2003/10/31 19:00
4	4863	(copper or Cu) and adhesion and seed	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2003/10/31 19:00
5	2164702	w or tungsten	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2003/10/31 19:01
6	3235	((copper or Cu) and adhesion and seed) and (w or tungsten)	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2003/10/31 19:01
7	235210	interconnect	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2003/10/31 19:01
8	1190	((copper or Cu) and adhesion and seed) and (w or tungsten)) and interconnect	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2003/10/31 19:02